

SPECIFICATION

REFOND P/N

RF-A2P08-WBE2-A1

R&D

Mass Production



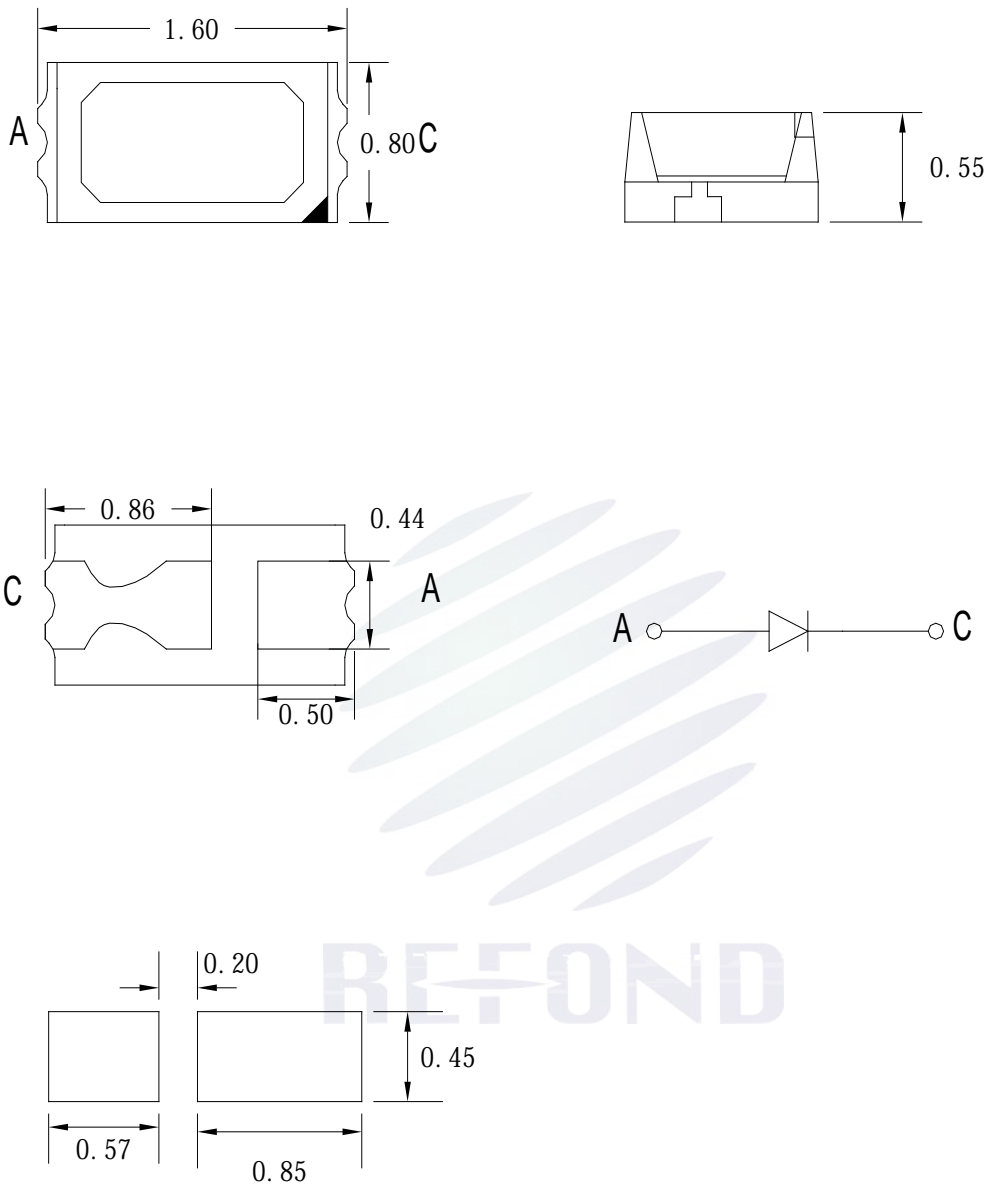
Contents

1. Description	3
1.1 General Description	3
1.2 Features	3
1.3 Application	3
1.4 Package Dimension	4
1.5 Product Parameters	5
1.6 Bin Range Of Forward Voltage and Luminous Intensity (IF=5mA)	BIN
(IF=5mA)	6
1.7 Typical Optical Characteristics Curves	8
2.1 Packaging Specification	12
2.1.1 Carrier Tape Dimension	12
2.1.2 Reel Dimension	12
2.1.3 Label Form Specification	13
2.2 Moisture Resistant Packing	13
2.3 Cardboard Box	13
2.4 Reliability Test Items And Conditions	14
2.5 Criteria For Judging Damage	15
3. SMT Reflow Soldering Instructions SMT	16
3.1 SMT Reflow Soldering Instructions SMT	16
4. Handling Precautions	18
4.1 Handling Precautions	18





1.4 Package Dimension



Notes

1. All dimensions units are millimeters.
2. All dimensions tolerances are ± 0.2 mm unless otherwise noted.

0.2



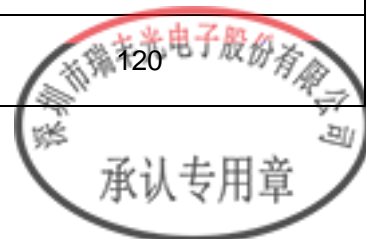
1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward Voltage	V_F	$I_F=5mA$	2.5	2.8	3.1	V
Reverse Current	I_R	$V_R=5V$	---	---	10	μA
Luminous Intensity	I_V	$I_F=5mA$	280	360	530	mcd
Viewing Angle	2 1/2	$I_F=5mA$	---	120	---	deg
Thermal Resistance.	R_{THJ-S}	$I_F=5mA$	---	---	300	$^{\circ}W$

Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	P_D	93	mW
Forward Current	I_F	30	mA
Peak Forward Current	I_{FP}	100	mA
Reverse Voltage	V_R	5	V
Electrostatic Discharge (HBM)	E_{SD}	2000	V
Operating Temperature	T_{OPR}	-40 ~ +100	
Storage Temperature	T_{STG}	-40 ~ +100	
Junction Temperature	T_J	120	



Notes

1. 1/10 Duty cycle, 10ms pulse width. 10ms, 1/10.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$. $\pm 0.1V$.
3. The above color coordinates measurement allowance tolerance is ± 0.005 . ± 0.005 .
4. The above luminous intensity measurement allowance tolerance $\pm 10\%$. $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED
8. ESD yield is over 90% at 2000V ESD (HBM). ESD protection during products handling is needed. 90% LED
ESD2000V

1.6 Bin Range Of Forward Voltage and Luminous Intensity (IF=5mA)

BIN (IF=5mA)

Table 1-3

VF	E2	F1	F2	G1	G2	H1
	2.5-2.6	2.6-2.7	2.7-2.8	2.8-2.9	2.9-3.0	3.0-3.1
IV mcd	I2	J1	J2			
	280-350	350-430	430-530			





1.7 Typical Optical Characteristics Curves

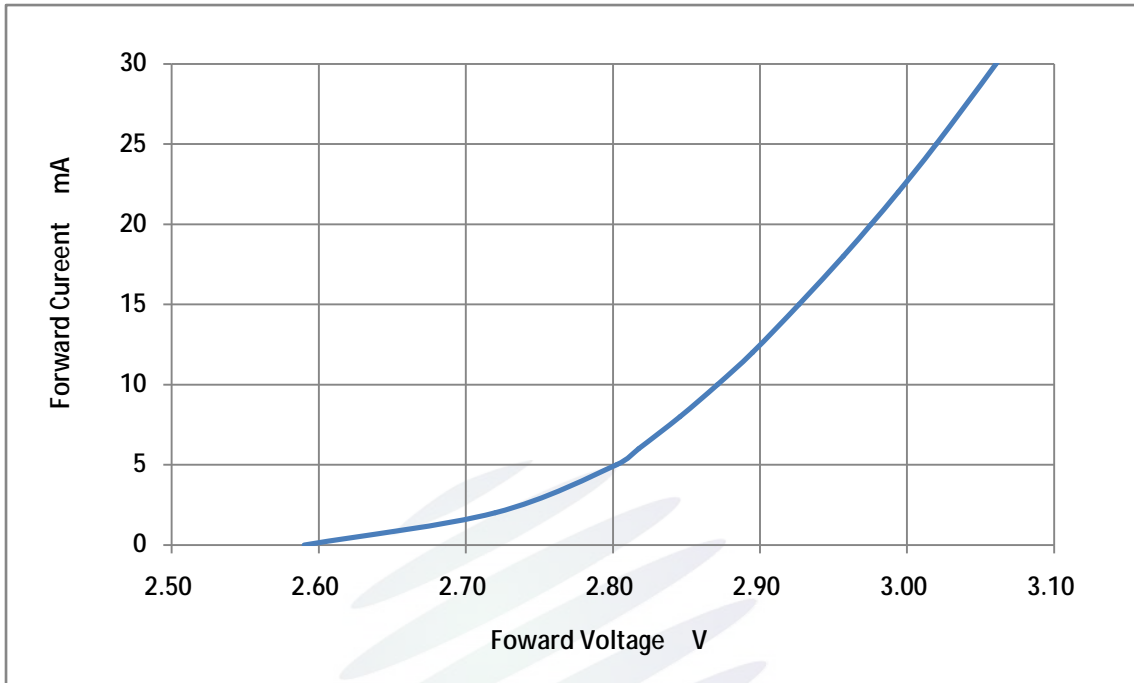


Fig. 1-7 Forward Voltage Vs Forward Current

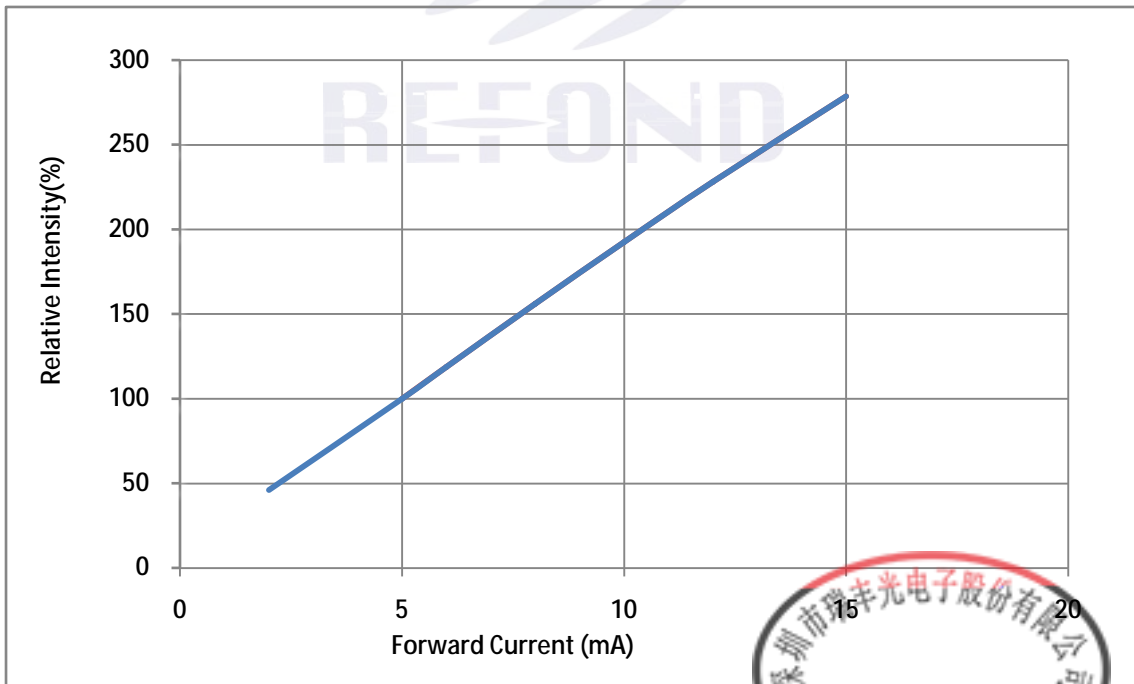


Fig. 1-8 Forward Current Vs Relative Intensity



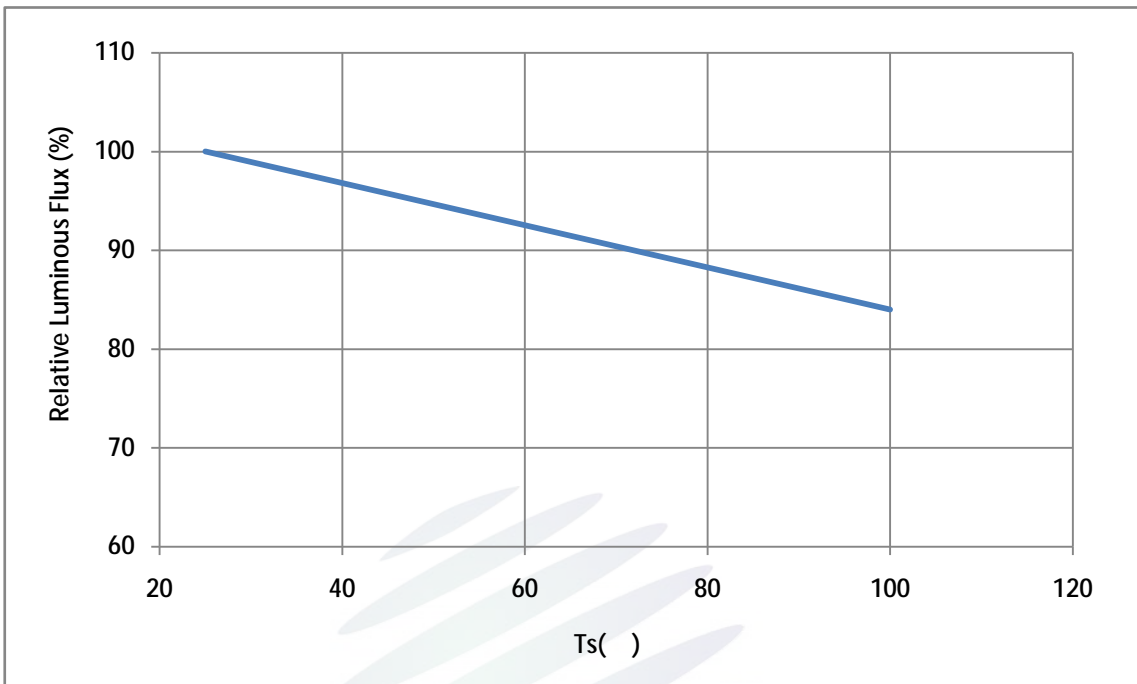


Fig. 1-9 Solder Temperature Vs Relative Intensity

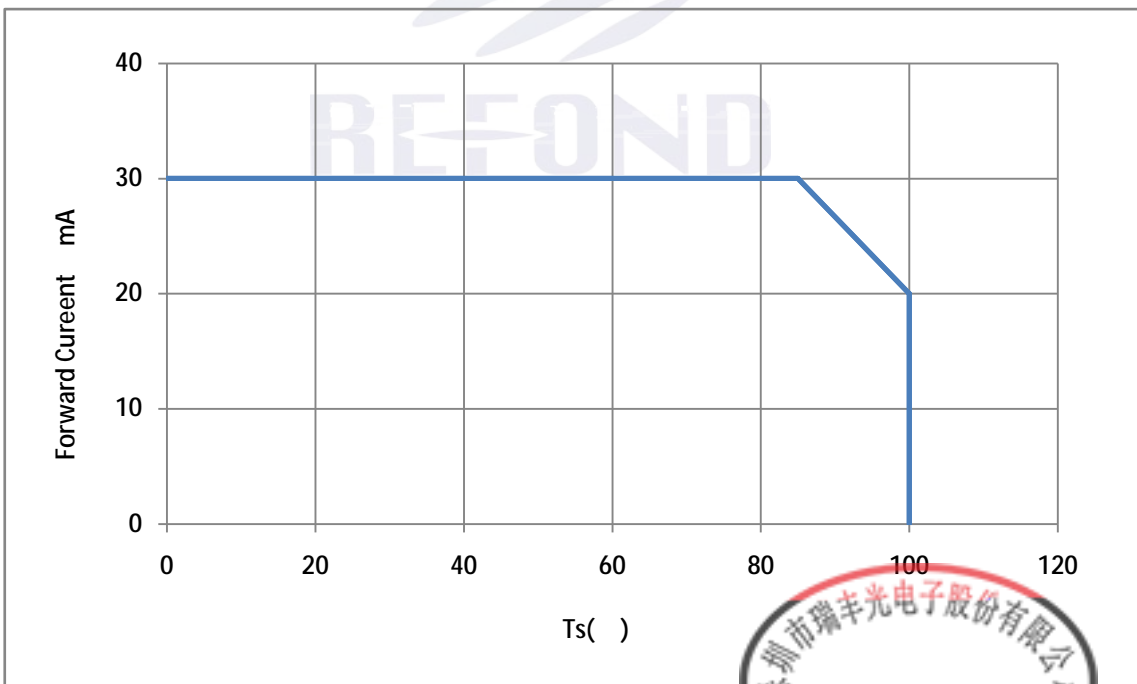


Fig. 1-10 Solder Temperature Vs Forward Current

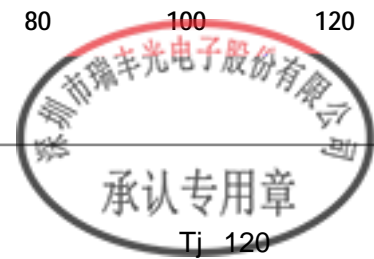


Fig. 1-11 Forward Voltage Vs Solder Temperature

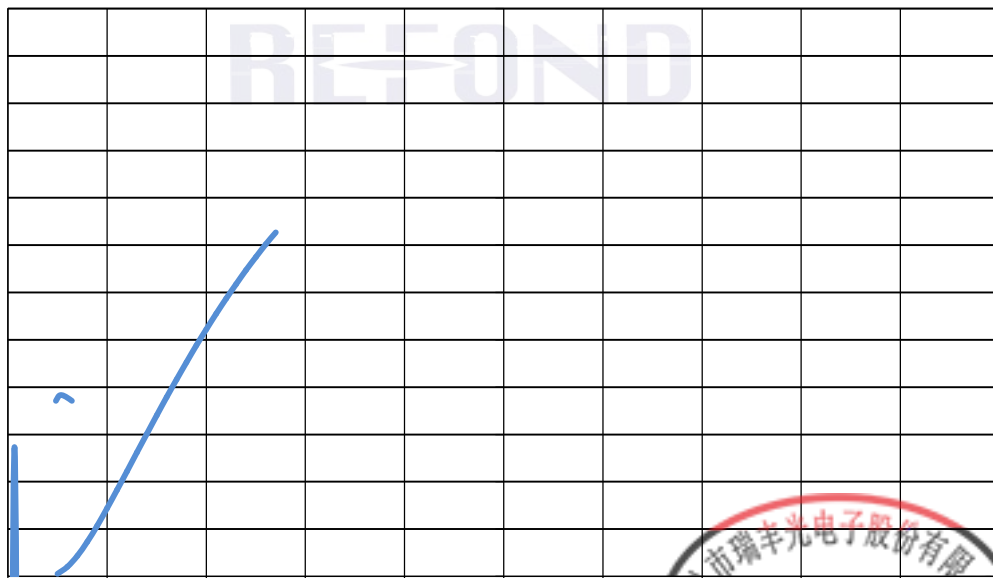
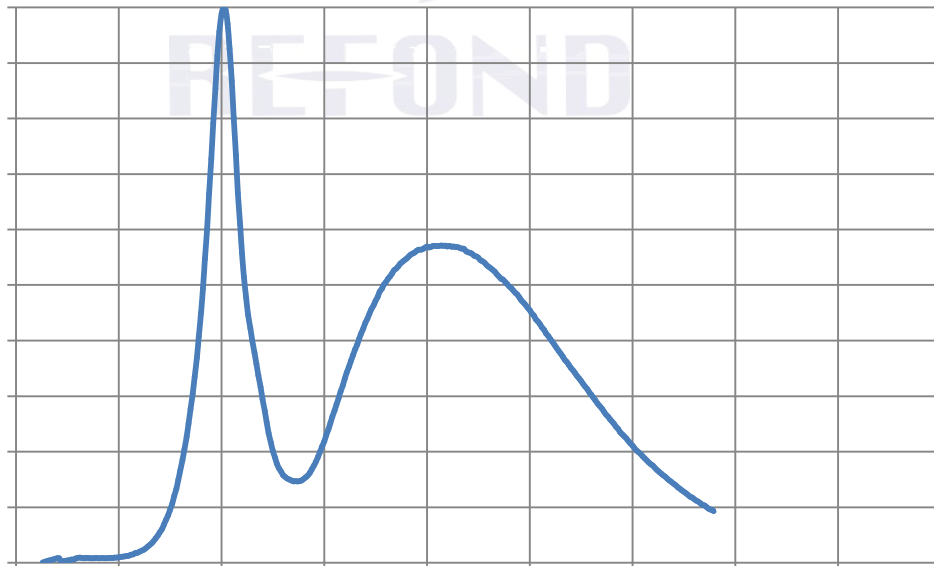


Fig. 1-12 Radiation diagram



2. Packaging

2.1 Packaging Specification

Package: 4000pcs/reel. 4000pcs

2.1.1 Carrier Tape Dimension

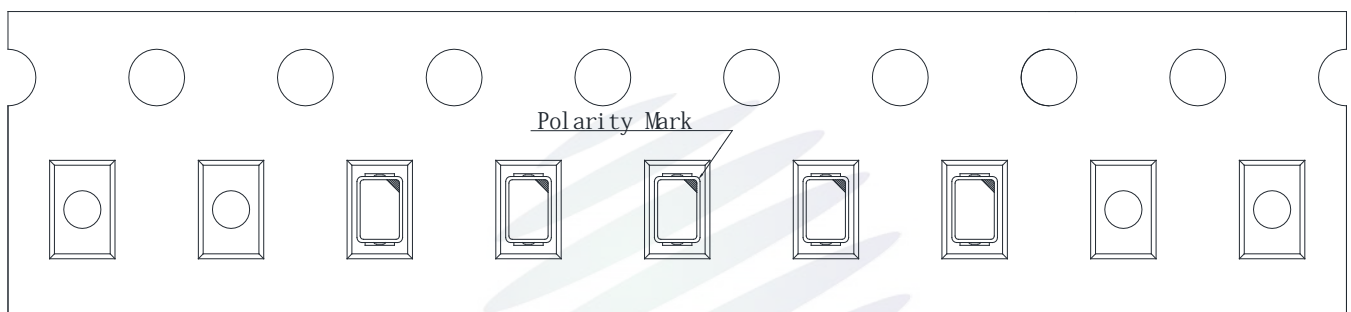
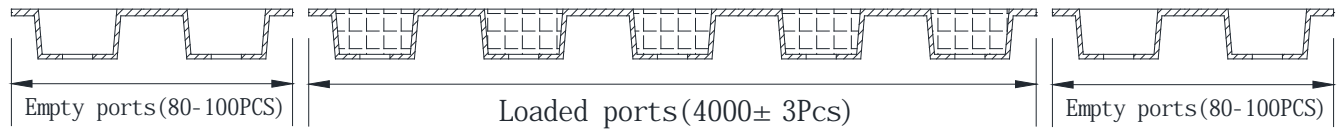


Fig.2-1 Carrier Tape Dimension

2.1.2 Reel Dimension

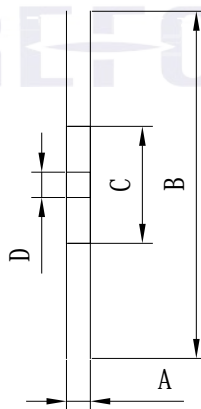
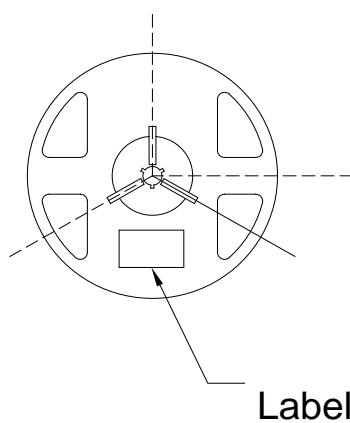


Fig.2-2 Reel Dimension

Table 2-1 Reel Dimension

A	8.0±0.1mm
B	178±1mm
C	60±1mm
D	13.0±0.5mm

Notes

The tolerances unless mentioned ±0.1mm. Unit : mm



2.1.3 Label Form Specification

Table 2-2 Specification

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
	Luminous flux
XY	Chromaticity Bin
V _F	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

Fig. 2-3 Label Form Specification

2.2 Moisture Resistant Packing

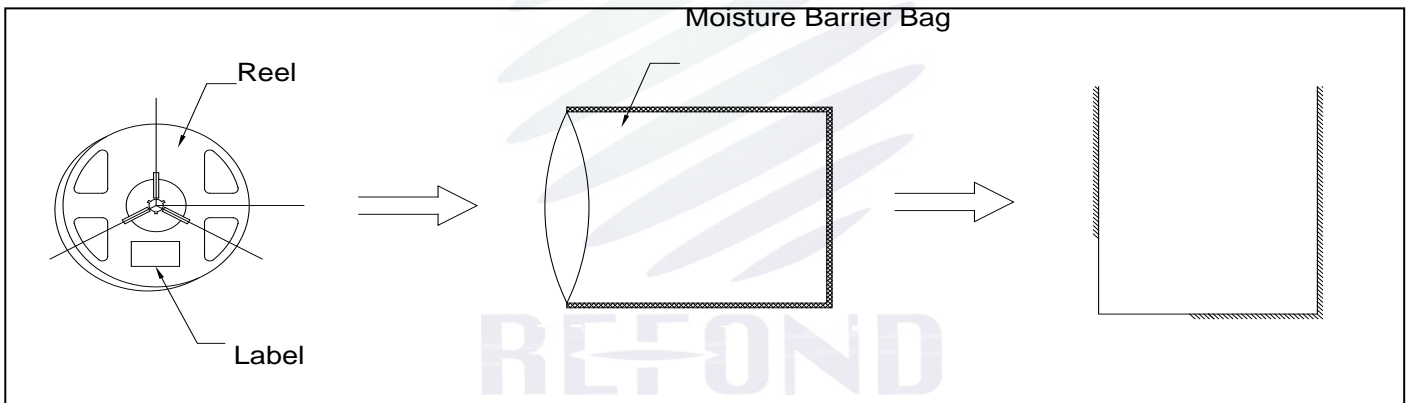


Fig.2-4 Moisture Resistant Packing

2.3 Cardboard Box



Fig.2-5 Cardboard Box





3. SMT Reflow Soldering Instructions SMT

3.1 SMT Reflow Soldering Instructions SMT

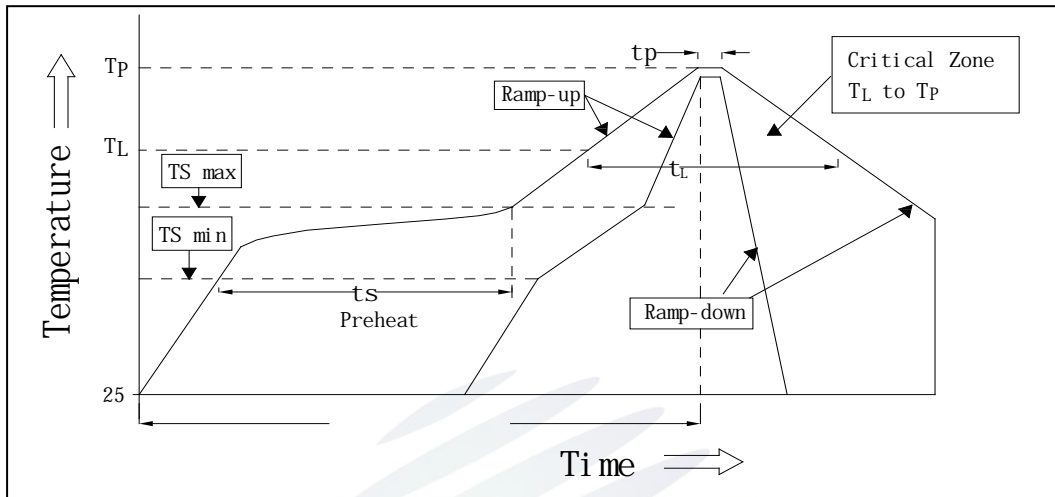
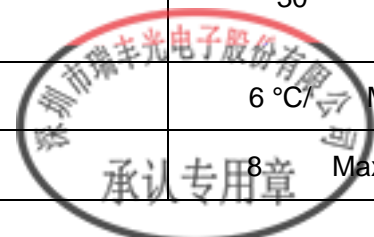


Fig.3-1SMT Reflow Soldering Instructions SMT

Table 3-1Reflow parameters

Average temperature rise speed	T_{smax} T_P	3 °C/ Max 3 °C/ s
Preheating: minimum temperature	(T_{smin})	150 °C
Preheating: Max temperature	(T_{smax})	200 °C
Preheating: Time	T_{smin} T_{smax}	60 - 120 60s-120s
Time limited to maintain high temperature: the temperature	(T_L)	217 °C
Time limited to maintain high temperature: The Time	(t_L)	60 Max 60s
Peak /Classification of temperature:	(T_P)	260 °C
Time limit classification of peak temperature time	t_p	10 Max 10s
(T_P) 5 °C actual peak temperature (TP)	Hold time within 5 °C with the	30 Max 30s
Cooling speed		6 °C/ Max 6 °C/ s
25 °C	Needed time from 25 °C to T_P	8 Max 8 minutes



Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings , LED will be damaged. 24 LED

(2)Whensoldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

(1) When do soldering by hand, keep the temperature of iron below less 300 less than 3 seconds. 300 3

(2) Soldering by hand should be done only one time.

3.1.2 Repairing

Repairing



4. Handling Precautions

4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement.

LED 100PPM.

(2) In order to prevent ex-ternal material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.

	LED	LED
	900PPM	900PPM
1500PPM.		

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor.

LED	LED	LED
	LED	

(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.



Fig 4-1 Handling Precautions

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified



Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	Recommended for use within 24 hours 24H

Baking

 60 ± 5

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Version History/

Date	Revisor	Version	Verifier	Remarks
2020/03/18	Huang nianhua	E0	Zhu yiming	New issue
2022/07/13	Lu Xian	E1	Zhu yiming	Template update





Declare

This specification is written both in English and in Chinese and the latter is formal.